Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S74	100	(wafer with lot) and defect and (layer with model)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/16 10:50
S75	83	(wafer with lot) and defect and (layer with model) and @ad<"20040202"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/16 10:48
S83	2	"6449749".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 08:47
S84	2143	716/4.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/21 12:37
S85	1478	700/121.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/13 09:40
S86	1327	700/121.CCLS. and @ad<"20040202"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 08:49
S87	20	(716/4.CCLS. or 700/121.CCLS.) and (defect with model) and lot and @ad<"20040202"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 08:50
S88	21	(partial\$2 with completed) and defect and (layer with model)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 08:34
S92	25	(partial\$2 with completed) and defect and (production with lot)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 16:20

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S93	63	steffan-paul-j.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/11 16:22
S94	3	"6901564".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 07:53
S95	40	("3751647" "4795964" "4835466" "4939681" "5067101" "5068547" "5070469" "5286656" "5301118" "5438527" "5486786" "5502643" "5625268" "5627083" "5629877" "5655110" "5703381" "5767542" "5773315" "5778202" "5790479" "5798649" "5822258" "5852581" "5867033" "5903012" "5966527" "5982929" "6005829" "6063132" "6066179" "6072804" "6075417" "6075418" "6118137" "6124143" "6134191" "6184048" "6289257" "6393602").PN. OR ("6901564").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/12 07:54
S96	4	(wafer with lot) and defect and (layer near2 model) and (product\$3 or manufactur\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 08:25
S97	0	((wafer with lot) and defect and (layer near2 model) and (product\$3 or manufactur\$3)).CLM.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 08:25
S98	0	(defect and (completed adj3 dies) and production and model).CLM.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 08:27
S99 <u> </u>	18	(disposition adj3 wafer) and production and model and defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 08:32
S10 0	0	((disposition adj3 wafer) and production and model and defect). CLM.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 08:33

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S10 1	0	((partially adj2 completed adj2 dies) and production and model and defect).CLM.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 08:33
S10 2	13	(one adj2 layer adj2 model).CLM.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 08:35
S10 3	1.	(wafer with lot) and defect and (layer with model) and (intermediate with process\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 08:44
S10 4	83	(wafer with lot) and defect and (layer with model) and @ad<"20040202"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 08:47
S10 5	0	((wafer with lot) and defect and (layer with model)).CLM.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 09:00
S10 6	1116	wafer and feed near3 forward	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/13 08:54
S10 7	768	wafer and feed near3 forward and layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/13 08:54
S10 8	367	wafer and feed near3 forward and layer and yield	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/13 10:11
S10 9	22	wafer and feed near3 forward and layer near3 model and yield	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/13 09:20
\$11 0	5	wafer and feed near3 forward and layer near3 model and yield and defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/13 09:20

S11 1	24	700/121.CCLS. and defect and yield and wafer and lot and intermediate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/13 09:41
S11 2	63	wafer and feed near3 forward and layer and yield and ("716"/\$.CCLS. or 700/121.CCLS.) and @ad<"20040202"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/13 10:12
S11 3	2350	716/4.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/21 12:37
S11 4	539	((partial\$4 near3 complet\$3) or incomplet\$3 or \$2finished) with ((wafer or lot or substrate) same defect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/06 08:39
S11 5	188	((partial\$4 near3 complet\$3) or incomplet\$3 or \$2finished) with ((wafer or lot or substrate) same defect) and ((subsequent or later or higher) with (layer or level))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/06 08:36
S11 6	4	((partial\$4 near3 complet\$3) or incomplet\$3 or \$2finished) with ((wafer or lot or substrate) same defect) and ((subsequent or later or higher) with (layer or level)) and disposition	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/06 08:36
S11 7	5	((partial\$4 near3 complet\$3) or incomplet\$3 or \$2finished) with ((wafer or lot or substrate) same defect) and "716"/\$.CCLS. and @ad<"20040202"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/06 08:40
S11 8	20	("5240866" "5539752" "5859698" "5886909" "5913105" "5991699" "6210983" "6246787" "6292582" "6338001").PN. OR ("6507933").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/06 08:46
S11 9	2	"6507933".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/13 09:32
S12 3	2	"20050273732"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/16 11:11